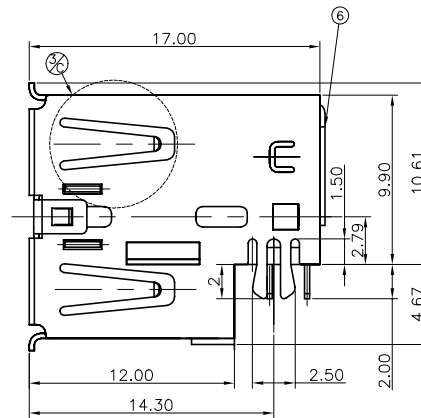
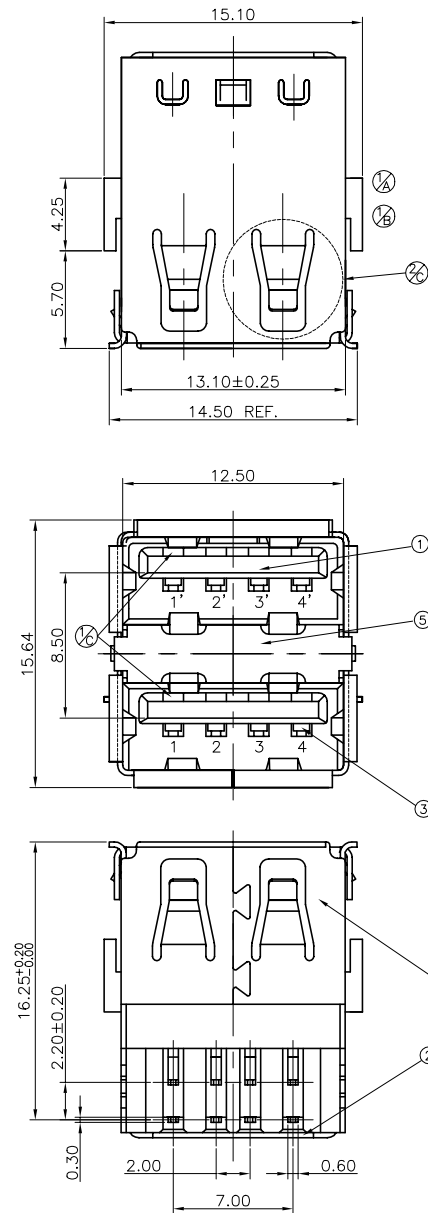
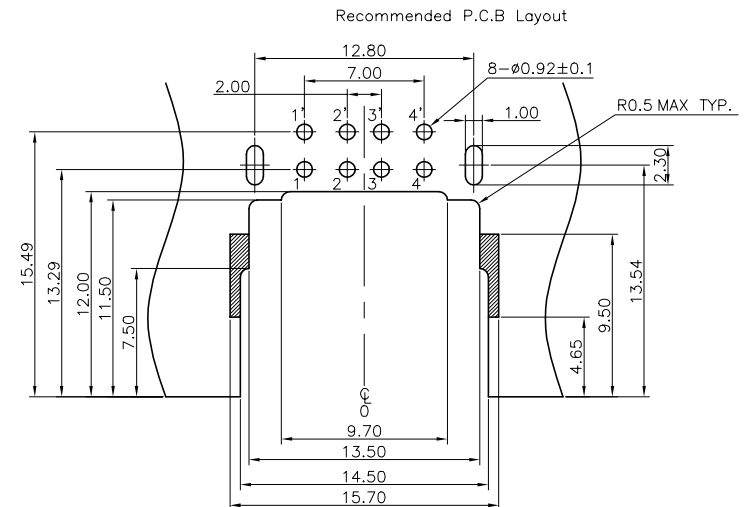




1 NOTE:
020122MR008□□25ZA

1. Selective plating
*S1,-05u" Min. gold in contact area/
100u" Min. Tin in solder area.
*S2,-Gold flash in contact area/
100u" Min. Tin in solder area.
*S3,-10u" Min. gold in contact area/
100u" Min. Tin in solder area.
*S4,-15u" Min. gold in contact area/
100u" Min. Tin in solder area.
*S5,-30u" Min. gold in contact area/
100u" Min. Tin in solder area.
*S6,-50u" Min. gold in contact area/
100u" Min. Tin in solder area.



6	SHELL	Brass	——	NICK PLATED
5	SHELL	Brass	——	NICK PLATED
4	SHELL	Brass	——	NICK PLATED
3	TERMINAL	Pho.Bronze	——	GOLD/TIN
2	BACK-CAP	LCP	BLACK	UL 94V-0
1	HOUSING	LCP	BLACK	UL 94V-0
NO. DESCRIPTION		MATERIAL	COLOR	REMARK

SUYIN
CONNECTOR

CUSTOMER COPY		TITLE: USB Series A Type Dual Port Dip Type		
PART NO.		020122MR008SX25ZA ②		
PART NO. (OLD)		2522AY-08XXX-Y		
DRAWING NO.		D 020122MR008SX25ZA		
SCALE	4:1	UNIT	mm	A4

ECN (DCN) NO.	REV	DATE	DESCRIPTION	CHANGE	APPRO.	GENERAL TOLERANCE UNLESS OTHERWISE NOTED
EC1T-021114-07	D	02/11/14	D1:增加新料號			Angle ±2°
EC1T-020808-07	C	02/08/08	C1:增加偷料孔;C2,C3:修改鐵殼彈片	宋勃逸	宋權哲	30 ~ 30 ±0.50
EC1T-020701-04	B	02/07/01	恢復撕破處	薛梅	宋權哲	10 ~ 10 ±0.30
	A	02/07/01	取消撕破處	薛梅	周孫宇	~ 10 ±0.15